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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10050300	01/15/2002	257	450i	2811	THAPPI

**APPLICANTS: Chen Yen-Ming; Lin Chia-Fu; Fan Yang-Tung; Huang Hong-Wen;
Chu Cheng-Yu;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	<input type="checkbox"/> DO NOT PUBLISH	<input type="checkbox"/> RESCIND	
Foreign priority claimed		<input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO
35 USC 119 conditions met		<input type="checkbox"/> yes <input type="checkbox"/> no	67,200-571
Verified and Acknowledged Examiners's initials			
TITLE : Microelectronic fabrication with corrosion inhibited bond pad			

U.S. DEPT. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg.	Print Fig.
		Application Examiner		
TERMINAL DISCLAIMER				

Primary Examiner

PREPARED FOR ISSUE

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